

DERWENT-ACC-NO: 1995-236623

DERWENT-WEEK: 199531

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TITLE: Low residual amount cream solder for  
nitrogen reflow - comprises powder solder, paste flux  
and N-substd. fatty acid amide

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PRIORITY-DATA: 1993JP-0313990 (November 22, 1993)

PATENT-FAMILY:

| PUB-NO        | PAGES | PUB-DATE     | MAIN-IPC |
|---------------|-------|--------------|----------|
| JP 07144293 A | 009   | June 6, 1995 | N/A      |
|               |       | B23K 035/22  |          |

APPLICATION-DATA:

| PUB-NO         | APPL-DATE | APPL-DESCRIPTOR   | APPL-NO |
|----------------|-----------|-------------------|---------|
| JP 07144293A   |           | N/A               |         |
| 1993JP-0313990 |           | November 22, 1993 |         |

INT-CL (IPC): B23K035/22, B23K035/363 , H05K003/34

ABSTRACTED-PUB-NO: JP 07144293A

BASIC-ABSTRACT:

Low residual amt. cream solder comprises: powder solder and paste flux. The cream solder contains N-substd. fatty acid amide of formula (1) or (2) and contains a low hygroscopic branched fatty acid alcohol having higher distillation pt. than the m.pt. of the solder and a low hygroscopic aromatic alcohol. R1CONHR2NHCOR1 (1); R3NHCOR4CONHR3 (2); R1 =

alkyl gp. of fatty acid;  
R2 = hydrocarbon of diamine; R3 = alkyl gp. of fatty acid  
amide; and R4 =  
hydrocarbon of dicarboxylic acid.

ADVANTAGE - The cream satisfies three requirements:  
printing workability,  
adhesiveness, solderability.

CHOSEN-DRAWING: Dwg.0/3

TITLE-TERMS: LOW RESIDUE AMOUNT CREAM SOLDER NITROGEN  
REFLOW COMPRISE POWDER  
SOLDER PASTE FLUX N SUBSTITUTE FATTY ACID AMIDE

DERWENT-CLASS: E19 M23 P55 V04 X24

CPI-CODES: E10-D03A; M23-A02;

EPI-CODES: V04-R04A5; X24-A01A;

CHEMICAL-CODES:

Chemical Indexing M3 \*01\*

Fragmentation Code

H401 H402 H481 H482 H721 H722 J0 J012 J3 J372  
L640 M210 M211 M212 M213 M214 M215 M216 M220 M221  
M222 M223 M224 M225 M226 M231 M232 M233 M262 M280  
M281 M282 M311 M312 M313 M314 M315 M316 M321 M322  
M323 M331 M332 M333 M340 M342 M381 M383 M391 M392  
M416 M620 M782 M903 M904 Q454 Q467 R021

Markush Compounds

199531-C7801-M

Chemical Indexing M3 \*02\*

Fragmentation Code

H721 H722 J0 J012 J3 J372 M210 M211 M212 M213  
M214 M215 M216 M220 M221 M222 M223 M224 M225 M226  
M231 M232 M233 M273 M282 M311 M312 M313 M314 M315  
M316 M321 M331 M332 M333 M340 M342 M382 M391 M416  
M620 M782 M903 M904 Q454 Q467 R021

Markush Compounds

199531-C7802-M

Chemical Indexing M3 \*03\*

Fragmentation Code

G010 G100 H401 H481 L660 L699 M210 M215 M216 M220  
M221 M222 M223 M224 M225 M226 M231 M232 M233 M272  
M280 M281 M311 M312 M313 M314 M315 M316 M320 M321

M322 M323 M331 M333 M340 M342 M373 M383 M391 M392  
M414 M416 M510 M520 M530 M531 M540 M620 M782 M903  
M904 Q454 Q467 R021  
Markush Compounds  
199531-C7901-M

SECONDARY-ACC-NO:

CPI Secondary Accession Numbers: C1995-108770

Non-CPI Secondary Accession Numbers: N1995-184828